

pSEMI MATERIAL DECLARATION FORM

Product:	PE43665
Ordering Codes:	PE43665A-Z
Description:	UltraCMOS® RF Digital Step Attenuator 1 MHz-2 GHz
Package:	20L 4x4 QFN
Environmental Compliance	EU RoHS Directive 2011/65/EC, REACH - EU ECHA SVHC, Arsenic Free , JIG 101 - EIA/EICTA/JEITA, Halogen Free - IEC61249-2-21, PFOS Free - 2006/122/EC, Antimony Trioxide Free
Lead Finish	NiPdAu
Availability	Now

Component	Material	CAS Number	Weight (mg)	%	PPM
Die	Aluminum oxide	1344-28-1	1.680017	4.09%	40,869.69
Die	Aluminum	7429-90-5	0.005110	0.01%	124.32
Die	Silicon	7440-21-3	0.000341	0.00%	8.29
Die	Arsenic	7440-38-2	0.000002	0.00%	0.04
Die	Boron	7440-42-8	0.000002	0.00%	0.04
Die	Phosphorus	7723-14-0	0.000007	0.00%	0.17
Die	Titanium	7440-32-6	0.000852	0.00%	20.72
Die	Tungsten	7440-33-7	0.017034	0.04%	414.39
Die	Cobalt	7440-48-4	0.000034	0.00%	0.83
Die	Copper	7440-50-8	0.000014	0.00%	0.33
Leadframe	Copper	7440-50-8	15.510800	37.73%	377,330.48
Leadframe	Iron	7439-89-6	0.373900	0.91%	9,095.85
Leadframe	Zinc	7440-66-6	0.019100	0.05%	464.64
Leadframe	Phosphorus	7723-14-0	0.004800	0.01%	116.77
Die Attach	Silver	7440-22-4	0.130900	0.32%	3,184.40
Die Attach	Epoxy Resin	9003-36-5	0.016400	0.04%	398.96
Die Attach	Diluent	26447-14-3	0.009800	0.02%	238.40
Die Attach	Dicyandiamide	461-58-5	0.001600	0.00%	38.92
Die Attach	Hardener	620-92-8	0.004900	0.01%	119.20
Gold Wire	Gold	7440-57-5	0.301300	0.73%	7,329.71
Plating	Nickel	7440-02-0	0.119300	0.29%	2,902.21
Plating	Palladium	7440-05-3	0.009700	0.02%	235.97
Plating	Gold	7440-57-5	0.000360	0.00%	8.76
Mold Compound	Silica Fused	60676-86-0	20.999700	51.09%	510,858.68
Mold Compound	Epoxy Resin	Trade secret	0.916000	2.23%	22,283.49
Mold Compound	Phenol Resin	Trade secret	0.916000	2.23%	22,283.49
Mold Compound	Carbon Black	1333-86-4	0.068700	0.17%	1,671.26
Total Weight (mg)			41.106672	100.00%	1,000,000